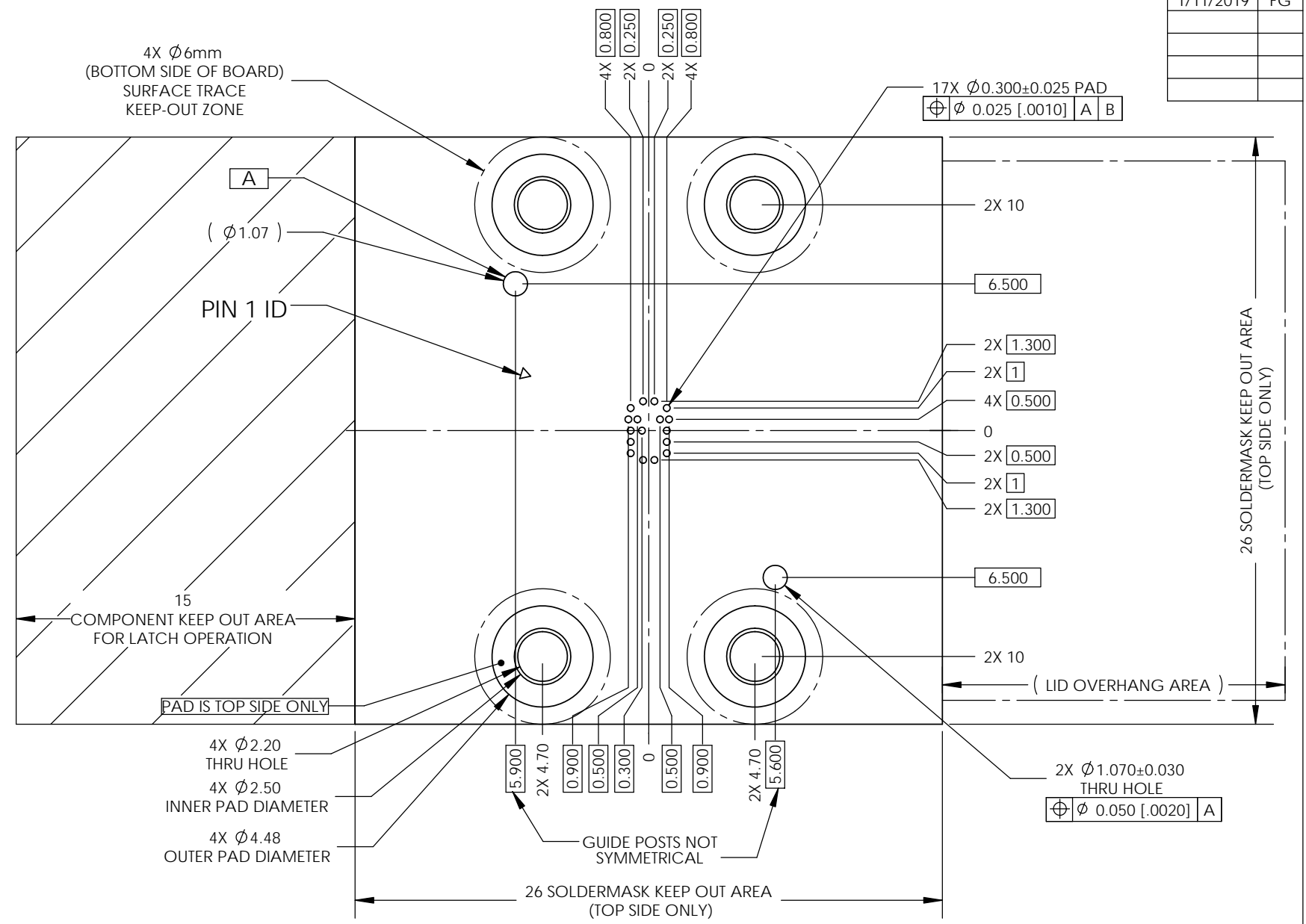
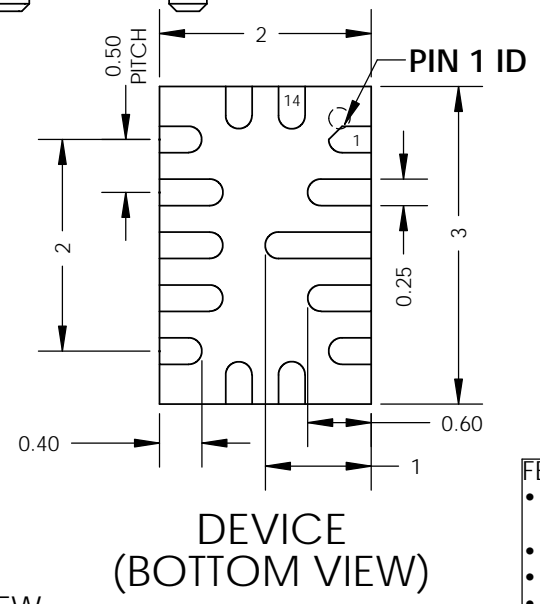
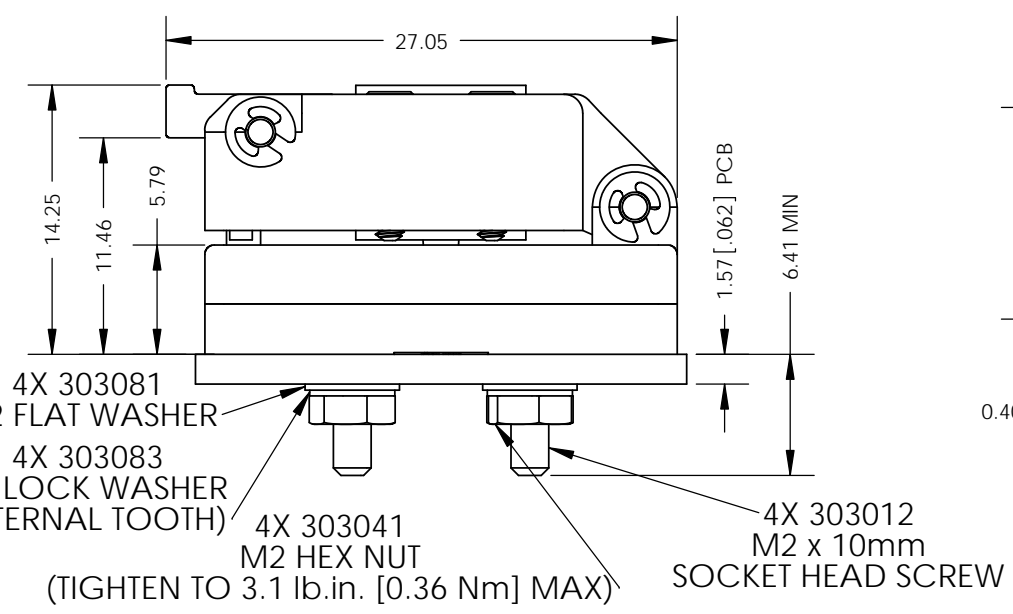
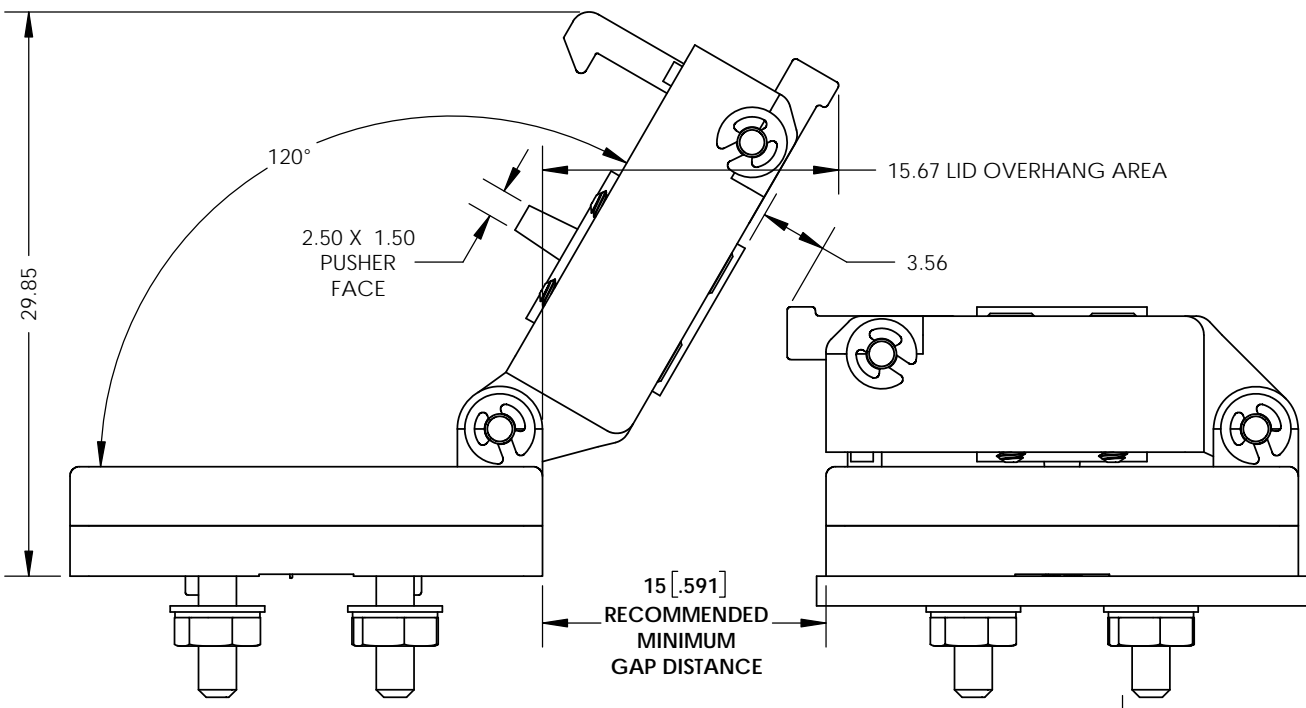
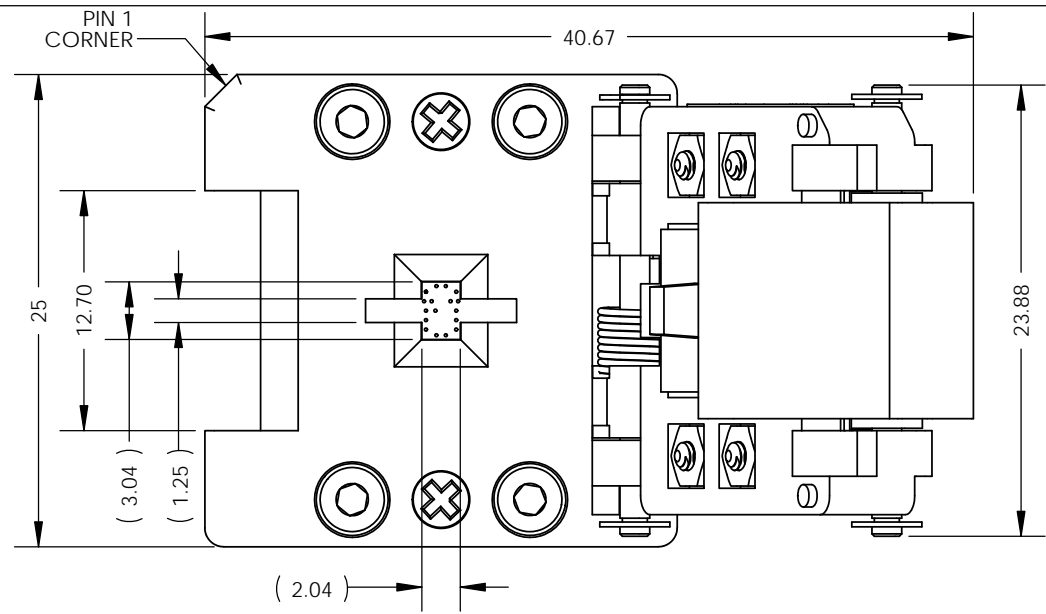


DATE	DRN
1/11/2019	FG



**TOP VIEW OF BOARD**

**NOTES:**

1. TOOLS REQUIRED FOR ASSEMBLY: 1.5mm ALLEN TORQUE DRIVER, 4mm HEX SOCKET DRIVER
2. PCB PAD PLATING: 30 µin. HARD Au OVER 300 µin. Ni OVER 1oz. MIN. Cu
3. CONTACT PLATING: 30 µin. Au OVER 75 µin. Ni
4. PLASTIC MATERIAL: ULTEM 2210EPR
5. ALL Au PADS SHOULD BE SAME THICKNESS.
6. BOARD LAYOUT TOLERANCE: ± 0.05mm UNLESS OTHERWISE SPECIFIED.
7. FILLED VIAS ARE ACCEPTABLE PROVIDED FILLER MATERIAL CAN WITHSTAND CONTACT FORCE AT BURN-IN TEMPERATURE.
8. SOCKET SHOULD FIT FREELY INTO PCB.

**P/N: 14QHC50A13020**

**PROPRIETARY**

- FEATURES:**
- PIN = H033LL2A (OPERATING AT 14.5gF)
  - SPRING LOADED PUSHER
  - TWEEZER SLOTS
  - 2X PINS ON PADS 2, 3, AND 11
  - 1X PINS ON REMAINING PADS

THIS DRAWING IS SUBJECT TO CHANGE WITHOUT NOTICE. PLEASE REQUEST A CURRENT DRAWING WHEN LAYING OUT BOARDS.	SIZE: B	NAME	DATE	DWG NO. S14QHC50A13020	SHEET 1 OF 1
	DRAWN	FG	1/11/2019	TITLE: C SERIES H-PIN QFN, 3.0 x 2.0mm DEVICE, 0.50mm PITCH, 17x H-PINS	
SCALE: VARIOUS	CHECKED	PT	1/14/2019		
UNITS: mmgs	ENG APPR.				
SOLIDWORKS CREATED FILE	MFG APPR.				